



#11
Amatt
a
NIT-215 9-5-02
arg

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

S. KONDO et al

Serial No. 09/637,570

Group Art Unit: 2812

Filed: August 14, 2000

Examiner: Ha T. Nguyen

For: POLISHING METHOD, METALLIZATION FABRICATION
METHOD, METHOD FOR MANUFACTURING SEMICONDUCTOR
DEVICE AND SEMICONDUCTOR DEVICE

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated April 24, 2002,
please amend the above-identified application as follows:

IN THE CLAIMS

Cancel claims 22 and 23 without prejudice or disclaimer,
and rewrite claims 1, 6, 9, 13, 14, 16, 17, 19, and 20 as
follows:

1. (Amended) A polishing method for a copper film by
chemical mechanical polishing, comprising forming a
protection-layer with a forming agent, polishing the
protection-layer away on a convex portion of the copper film,
oxidizing a surface of the convex portion of the copper film